

G4L3-SD1-LAX3

HPC/AI Server - 4U DP NVIDIA HGX™ H200 8-GPU DLC



Key Features

- Liquid-cooled NVIDIA HGX™ H200 8-GPU
- CPU+GPU direct liquid cooling solution with leak detection
- 900GB/s GPU-to-GPU bandwidth with NVIDIA® NVLink™ and NVSwitch™
- Dual 5th/4th Gen Intel® Xeon® Scalable Processors
- Dual Intel® Xeon® CPU Max Series
- 8-Channel DDR5 RDIMM, 32 x DIMMs
- Dual ROM Architecture
- Compatible with NVIDIA BlueField®-3 DPUs and ConnectX®-7 NICs
- 2 x 10Gb/s LAN ports via Intel® X710-AT2
- 2 x M.2 slots with PCIe Gen3 x2 and x1 interface
- 8 x 2.5" Gen5 NVMe/SATA hot-swap bays
- 4 x FHHL dual-slot PCIe Gen5 x16 slots
- 8 x FHHL single-slot PCIe Gen5 x16 slots
- 4+4 3000W 80 PLUS Titanium redundant power supplies

Specification

Dimensions	4U (W447 x H175.3 x D920 mm)	PCIe Expansion Slots	4 x FHHL dual-slot PCIe Gen5 x16 8 x FHHL single-slot PCIe Gen5 x16
Motherboard	MSB3-PE0	I/O Ports	Front: 2 x USB 3.2 Gen1, 1 x VGA, 2 x RJ45, 1 x MLAN (default) Rear: 1 x MLAN
CPU	5th/4th Generation Intel® Xeon® Scalable Processors Intel® Xeon® CPU Max Series Dual processor, TDP up to 385W	Backplane Board	PCIe Gen5 x4 or SATA 6Gb/s
Socket	2 x LGA 4677 (Socket E)	TPM	1 x TPM header (SPI), Optional TPM2.0 kit: CTM010
Chipset	Intel® C741	Power Supply	4+4 3000W 80 PLUS Titanium redundant power supplies AC Input: 115-240V *The system power supply requires C19 power cord.
Memory	8-Channel DDR5 RDIMM, 32 x DIMMs [5th Gen Intel Xeon] Up to 5600 MT/s, 4400 MT/s [4th Gen Intel Xeon] Up to 4800 MT/s, 4400 MT/s [Intel Xeon Max Series] Up to 4800 MT/s, 4400 MT/s	System Management	ASPEED® AST2600 Baseboard Management Controller GIGABYTE Management Console web interface
Lan	Front: 2 x 10Gb/s LAN (1 x Intel® X710-AT2), Support NCSI function 1 x 10/100/1000 Mbps Management LAN Rear: 1 x 10/100/1000 Mbps Management LAN	System Fans	Motherboard: 2 x 60x60x56mm, 2 x 60x60x76mm PCIe slots: 4 x 80x80x56mm (15,500rpm) GPU tray: 4 x 60x60x38mm (24,000rpm)
Video	Integrated in ASPEED® AST2600 - 1 x VGA port	Operating Properties	Operating: 10°C~35°C, 8%~80% (non-condensing) Non-operating: -40°C~60°C, 20%~95% (non-condensing)
Storage	Front hot-swap: 8 x 2.5" Gen5 NVMe/SATA Internal M.2: 1 x M.2 (2280/22110), PCIe Gen3 x2 1 x M.2 (2280/22110), PCIe Gen3 x1	Packaging Content	1 x G4L3-SD1-LAX3 6 x Carriers 1 x L-shape Rail kit
RAID	Intel® SATA RAID 0/1/10/5	Ordering Part Numbers	6NG4L3SD1DR000LBX3*
Modular GPU	Liquid-cooled NVIDIA HGX™ H200 with 8 x SXM GPUs	Optional Parts	- C19 power cord 125V/15A (US): 25CP1-018000-Q0R - C19 power cord 250V/16A (EU): 25CP3-01830H-Q0R - C19 power cord 125V/15A (JP): 25CPA-01830B-Q0R



Learn more at: <https://www.gigabyte.com/Enterprise>

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